

WHAT IS CLAIMED IS:

1. A flip chip package structure for an image sensor,
comprising:

a semi-conductor image sense chip having a top face
5 attached to a bottom face of a glass plate and multiple electric contacts
formed on the semi-conductor image sense chip; and
a conductive interconnection circuit formed on the bottom
face of the glass plate, the conductive interconnection circuit having
multiple first solder points each electrically connected to a
10 corresponding one of the electric contacts of the semi-conductor image
sense chip and multiple second solder points formed on one side of the
glass plate, the multiple second solder points adapted to be electrically
connected to a printed circuit, the periphery and the bottom face of the
glass plate covered with an opaque mask, the opaque mask having a
15 through hole defined for allowing the semi-conductor image sense chip
extending through the opaque mask.

2. The flip chip package structure as claimed in claim 1,
wherein the semi-conductor image sense chip has a periphery
underfilled with jelly-like material to form an airtight condition.

20 3. The flip chip package structure as claimed in claim 2,
wherein the electric contacts are bumps.

4. The flip chip package structure as claimed in claim 2,
wherein the electric contacts are bonding pads and each has a metal

soldering ball planted thereon.

5. The flip chip package structure as claimed in claim 1, wherein the multiple second solder points are arranged separately juxtaposed relative to one another.

5 6. The flip chip package structure as claimed in claim 1, wherein the multiple second solder points are arranged in an array.

7. An image sense module comprising:

 a semi-conductor image sense chip having a top face attached to a bottom face of a glass plate and multiple electric contacts
10 formed on the semi-conductor image sense chip;

 a conductive interconnection circuit formed on the bottom face of the glass plate, the conductive interconnection circuit having multiple first solder points each electrically connected to a corresponding one of the electric contacts of the semi-conductor image
15 sense chip and multiple second solder points formed on one side of the glass plate, the multiple second solder points adapted to be electrically connected to a print circuit; and

 a lens set secured on the glass plate, the lens set including a holder perpendicularly attached to a top face of the glass plate and
20 having a skirt downward extending from the holder, a channel defined in one side of the skirt for allowing the conductive interconnection circuit extending through the holder.

8. The image sense module as claimed in claim 7, wherein the

electric contacts are bonding pads and each has a metal soldering ball
planted thereon, and the periphery and the bottom face of the glass
plate are covered with an opaque mask, the opaque mask having a
through hole defined for allowing the semi-conductor image sense chip
5 extending through the opaque mask.

9. The image sense module as claimed in claim 8, wherein the
multiple second solder points are arranged separately juxtaposed
relative to one another.

10. The image sense module as claimed in claim 8, wherein the
10 multiple second solder points are arranged in an array.

11. The image sense module as claimed in claim 7, wherein the
electric contacts are bumps, and the periphery and the bottom face of
the glass plate are covered with an opaque mask, the opaque mask
having a through hole defined for allowing the semi-conductor image
15 sense chip extending through the opaque mask.

12. The image sense module as claimed in claim 11, wherein
the multiple second solder points are arranged separately juxtaposed
relative to one another.

13. The image sense module as claimed in claim 11, wherein
20 the multiple second solder points are arranged in an array.